

ADLINK Green AI Solution

ADLINK
LEADING EDGE COMPUTING

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Green Transition: Embracing Environmental Challenges and Building a Sustainable Future

As modern society advances, environmental issues have worsened. Excessive waste and resource consumption are straining our planet. Every day, thousands of tons of waste are dumped or incinerated, causing land pollution and releasing greenhouse gases that intensify global warming. Plastic products, difficult to decompose, further pollute soil and oceans, threatening ecosystems and human health.

Rising living standards and technological progress have driven up electricity demand, increasing reliance on coal and natural gas. This produces large amounts of carbon dioxide and harmful emissions, worsening air pollution and accelerating climate change. This cycle erodes our quality of life, with more frequent extreme weather events.

Embracing ESG (Environmental, Social, and Governance) principles is essential. Reducing waste, improving energy efficiency, and promoting resource recycling are key steps. Individuals can help by choosing sustainable products, conserving energy, and supporting green consumption. A green transition — driven by renewable energy and the circular economy — is both a response to the crisis and a strategy for future development. When governments, businesses, and individuals work together, true green prosperity is possible.





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Edge AI for Environmental Protection and Sustainability

As environmental challenges grow, Edge AI (Artificial Intelligence at the Edge) is becoming essential for environmental protection and sustainability.
Edge AI processes data directly on devices (like sensors and edge servers) without relying on cloud computing, improving efficiency and reducing environmental impact.

Key Contributions of Edge AI:

1 Reducing Energy Consumption and Carbon Emissions

- Local data processing reduces network and cloud-based computation, lowering energy use.
- In smart buildings and cities, Edge AI optimizes energy use for heating, cooling, and lighting, cutting energy waste and emissions.

2 Promoting Recycling and Waste Management

- Edge AI improves waste sorting with image recognition, increasing recycling efficiency.
- In manufacturing, it detects material waste in real time and adjusts operations to reduce waste.

3 Optimizing Traffic and Lowering Emissions

- Smart traffic systems use Edge AI to adjust traffic flow and reduce congestion and idle time, cutting fuel use and emissions.
- Supports autonomous driving by improving efficiency and reducing unnecessary fuel consumption.

4 Monitoring the Environment and Protecting Ecosystems

- Sensors powered by Edge AI monitor air and water quality, wildlife activity, and detect illegal logging or poaching.
- Enables early disaster warnings (e.g., wildfires) for faster response and reduced damage.

5 Improving Manufacturing and Supply Chain Efficiency

- Edge AI optimizes transportation routes, cargo loads, and delivery schedules to reduce fuel use and emissions.
- Edge AI enhances decision-making and efficiency, driving the transition to a greener, more sustainable future.

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AI Goes Green — Across Every Sector



Smart Energy Management

Intelligent Waste Sorting and Recycling

Eco-Friendly Transportation

Precision Agriculture

Environmental Monitoring and Conservation

Accelerate Your Success with ADLINK *Green AI* Solution

Recycling supports environmental sustainability by improving waste management and conserving resources. Automated sorting and compacting technologies boost efficiency, while incentives like deposit refunds encourage responsible habits. This reduces landfill waste, lowers carbon emissions, and preserves resources. Smart sorting and recycling solutions in urban areas promote sustainable consumption and waste reduction.

ADLINK's "Green AI" solutions enhance sorting and recycling systems with industrial-grade AI technology, ensuring reliable performance in tough environments and improving both efficiency and user experience.

Benefits

- Compact AI Powerhouse with Industrial Grade Resilience
- Seamless Sensor Integration
- Versatile Application Scope
- Robust Solution Network

Service Flow

1. In-depth discussion over project details and requirements
2. Recommending a suitable edge AI platform
3. Customer testing and feedback
4. Quick PoC and implementation



Reverse Vending Machine (RVM)

Recycling Builds a Better Future

Reverse Vending Machines (RVMs) are designed to automate and streamline the collection and sorting of recyclable materials such as cans, plastic bottles, and glass bottles. By incentivizing recycling through rewards or credits, RVMs encourage environmental responsibility while improving waste management efficiency.
Widely used in urban areas, public spaces, and retail environments, RVMs offer a smart solution to reduce waste, support sustainability initiatives, and promote a circular economy.

Challenges & Requirements

- Material Sorting: Accurate identification of recyclables.
- User-Friendly: Easy and quick to use.
- Reliable Operations: High uptime in various conditions.
- Smart Connectivity: IoT for monitoring and maintenance.

Solutions

- AI-Powered Vision System: Use cameras with deep learning models trained to recognize materials like plastics, metals, paper, and glass.
- Multi-Sensor Fusion: Combine vision with NIR (Near-Infrared), X-ray, or hyperspectral sensors to enhance accuracy for hard-to-identify materials.
- Fast Processing: Instant feedback using edge computing to ensure quick sorting decisions.
- Industrial-Grade Hardware: Weatherproof casings and vibration-resistant components for indoor/outdoor reliability.
- Touchscreen Interface with Visual Prompts: Simple, intuitive UI with images and icons for different material types.

Fanless Edge AI Platforms





Compact Edge AI Platform **Expandable Edge AI Platform**

- **F** **Feature**: Robust, compact, industrial-grade fanless design
- **A** **Advantage**: Delivers high-performance computing and advanced AI processing at the edge
- **B** **Benefit**: Purpose-built to operate reliably in harsh environments

Industrial Computers





Single Board Computes **Open Standard Module™**

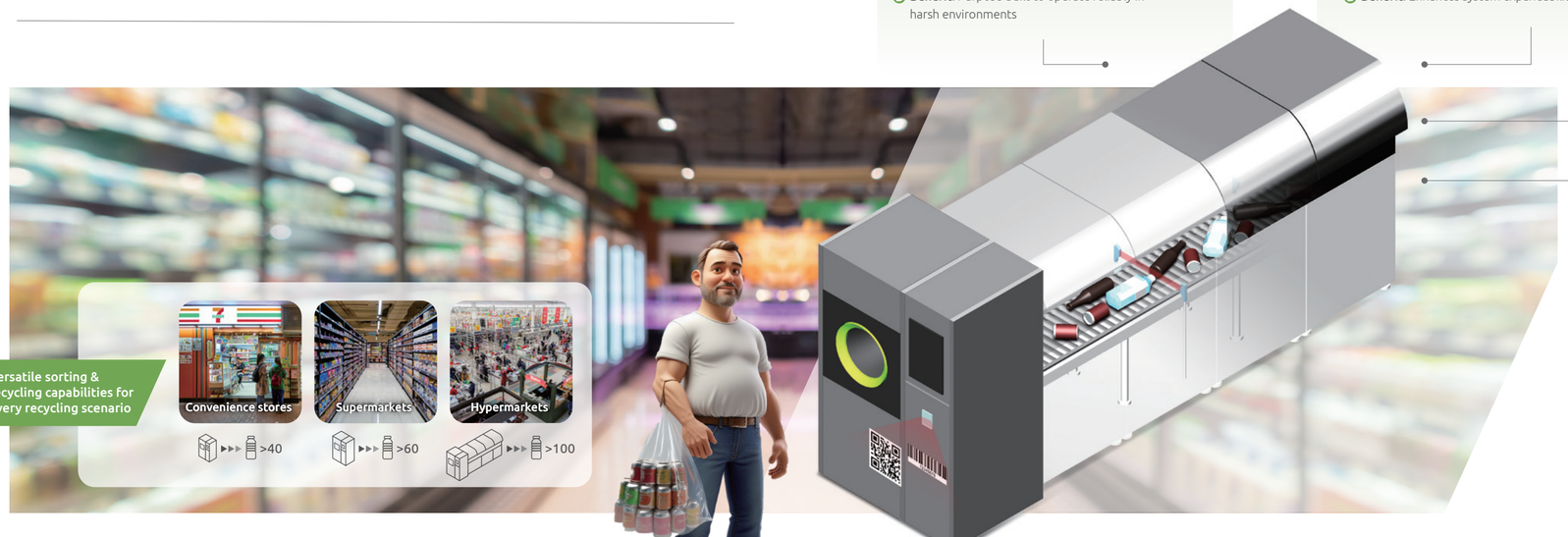
- **F** **Feature**: Compact form factors with low power consumption
- **A** **Advantage**: Offers flexible performance options
- **B** **Benefit**: Enhances system expandability and flexibility

Human-Machine Interface



Industrial Touch Monitors

- **F** **Feature**: Wide range of screen sizes (7" to 43")
- **A** **Advantage**: Value-Added Features: optimized touch, brightness, anti-glare, and more for outdoor use.
- **B** **Benefit**: Ensures long-term durability and reliability in harsh industrial environments



Embedded GPU Modules and Cards





MXM GPU Modules **PCIe Graphics Cards**

- **F** **Feature**: ADLINK is Elite member of the NVIDIA Partner Network, and Titanium Partner of Intel®
- **A** **Advantage**: Scalable solutions with advanced GPU integration
- **B** **Benefit**: Provides flexible integration options for customized system configurations

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Product Selection Guide

Compact Edge AI Platforms

NVIDIA Elite Partner





Model Name		DLAP-211-Orin Super		DLAP-411-Orin Supreme	
AI Performance		34 TOPS	67 TOPS	200 TOPS	275 TOPS
System	GPU	512-core NVIDIA Ampere architecture GPU with 16 Tensor Cores	1024-core NVIDIA Ampere architecture GPU with 32 Tensor Cores	NVIDIA Ampere architecture with 1792 NVIDIA® CUDA® cores and 56 Tensor Cores	NVIDIA Ampere architecture with 2048 NVIDIA® CUDA® cores and 64 Tensor Cores
	CPU	6-core Arm® Cortex®-A78AE v8.2 64-bit CPU 1.5MB		8-core Arm®Cortex®-A78AE v8.2 64-bit CPU 2MB L2 + 4MB L	12-core Arm®Cortex®-A78AE v8.2 64-bit CPU 3MB L2 + 6MB L3
	RAM	4GB	8GB	32GB	64GB
	Storage	128GB M.2 2242 PCIe Gen 3x4		64GB eMMC 5.1	
	OS	Linux® Ubuntu		Linux® Ubuntu	
Back I/O Interfaces	USB	1x USB 2.0 OTG		1x USB 3.2 Gen2 Type-C (OTG)	
Expansion Slots	Mini PCIe	1x PCIe mini card slot		-	
Power Supply	DC Input	12V		24V	
Mechanical	Dimensions (W x D x H)	148mm x 120mm x 52mm (DLAP-211-Orin NX/Orin Nano) 148mm x 120mm x 64mm (DLAP-211-Orin NXS/Orin NanoS)		175x 145x 85mm	
	Weight	Gross 1.7kg/ Net 1.01kg (DLAP-211-Orin NX/Orin Nano) Gross 1.85kg/ Net 1.16kg (DLAP-211-Orin NXS/Orin NanoS)		2.2 kg	
	SMA Antenna Connector	4		-	
	Operating Temperature	20°C to 70°C with 0.6m/s airflow, at 10W -20°C to 60°C with 0.6m/s airflow, at 15W -20°C to 50°C with 0.6m/s airflow, at 25W -20°C to 40°C with 0.6m/s airflow, at MAXN, Need to use industrial grade parts (which Tamb spec is 85°C) for mPCIE interferface parts.		For 32GB -20°C to 60°C with 0.6m/s airflow, at 40W -20°C to 55°C with 0.6m/s airflow, at MAXN For 64GB -20°C to 55°C with 0.6m/s airflow, at 50W -20°C to 40°C with 0.6m/s airflow, at MAXN	

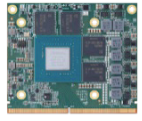
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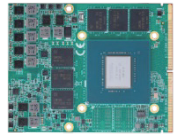
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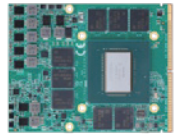
Expandable Edge AI Platforms



Model Name		DLAP-5200 Series	
System	GPU	NVIDIA RTX A1000, A2000, T1000, Intel A370M (MXM Support)	
	CPU	12/13th Gen. Intel® Core™ Processors, up to 65W	
	Chipset	Intel® R680E Chipset	
	RAM	Max. 128GB, DDR5 4x SO-DIMMs, up to 4800MHz	
	Storage	2x 2.5" SATA 6Gb/s internal drive bays	
	OS	Windows 10 IoT LTSC, Windows 10 Professional, and Windows 11 IoT, Ubuntu 22.04	
I/O Interfaces	Display	2x HDMI 1.4b 3x DisplayPort 1.4(1x from MXM module)	2x HDMI 1.4b 6x DisplayPort 1.4(4x from MXM module)
	Ethernet	6x 2.5GbE with TSN supported (i225)	3x 2.5GbE with TSN supported (i225)
	Serial Ports	2x RS-232/422/485	2x RS-232/422/485, 1x RS-232
	USB	4x USB 3.2 Gen2 (Type A), 2x USB 3.1 Gen2 (Type A)	
	M.2	1x M.2 2280 M Key, 1x M.2 2230 E Key	
	Audio	-	
	TPM 2.0	Yes	
Power Supply	DC Input	12-24Vdc (terminal block)	
	AC Input	Optional: 280W (12V/20A) AC/DC adapter	
Environmental	Operating Temperature	-20°C to 50°C (35W CPU) -20°C to 40°C (65W CPU)	







Model Name	EGX-MXM-AD2000	EGX-MXM-AD3500	EGX-MXM-AD5000
GPU Architecture	NVIDIA RTX™ 2000 ADA AD107-975 GPU	NVIDIA RTX™ 3500 ADA AD104-925 GPU	NVIDIA RTX™ 5000 ADA AD103-950-955 GPU
Memory	8GB GDDR6	12GB GDDR6	16GB GDDR6
CUDA Cores	3,072	5,120	9,728
TFLOPS Peak	15	23	42.6
Tensor Cores	96	160	304
RT Cores	24	40	76
PCIe Interface	PCIe Gen4 x8	PCIe Gen4 x16	PCIe Gen4 x16
GDDR	8GB GDDR6	12GB GDDR6	16GB GDDR6
Displays	3 x DP 1.4a, HDMI 2.1	4 x DP 1.4a, HDMI 2.1	4 x DP 1.4a, HDMI 2.1
Dimensions	82 x 70mm (Type A)	82 x 105mm (Type B)	82 x 105mm (Type B)
Power	60W	115W	115W
Software	Windows 10, 11 & Linux Drivers, 64-bit		

Product Selection Guide

Expandable Edge AI Platforms



Model Name		DLAP-8100 Series
System	GPU	NVIDIA RTX 6000 ADA
	CPU	Intel® 14th/13th/12th-Gen Core™ 35W/ 65W LGA1700 CPU
	Chipset	Intel® R680E Chipset
	RAM	Max. 192GB, DDR5 4800MHz (4x SODIMM slots)
	Storage	4x 2.5" SATA external swappable trays (3x SATAIII, 1x USB-to-SATA)
	OS	Windows 10 IoT LTSC, Windows 10 Professional, and Windows 11 IoT, Ubuntu 22.04
I/O Interfaces	Display	2x DP++ and 2x HDMI
	Ethernet	3x 2.5GBE with TSN supported (i225). 1x vPro supported
	Serial Ports	COM1/2: RS-232/422/485, COM3/4: RS-232
	USB	4x USB 3.2 Gen2 (Type A), 2x USB 3.2 Gen1 (Type A)
	M.2	1x M.2 2230 Key E (PCIe Gen3 x1), 1x M.2 3042/3052 Key B (PCIe Gen3 x1 / USB3) 1x M.2 2280 Key M, NVMe/SATA (PCIe Gen3 x4/ SATA)
	Digital IO	8-ch DI and 8-ch DO
	Audio	Line-out, Mic-in
	TPM 2.0	Yes
	Expansion slot	1x PCIe x16, 2x PCIe x8 (signal x4), 1x PCIe x1
Power Supply	DC Input	12-24Vdc (terminal block
	AC Input	100-240 VAC
Environmental	Operating Temperature	-20°C to 60°C(without PEG card)



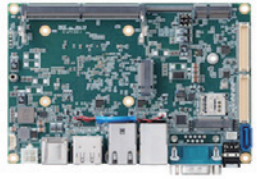


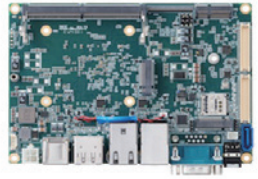


Model Name		RTX 4000 ADA	RTX 5000 ADA	RTX 6000 ADA
Graphic Core	Graphic Architecture	NVIDIA Ada Lovelace AD104	Ada Lovelace AD102	Ada Lovelace AD102
	GPU	RTX 4000 Ada	RTX 5000 Ada	RTX 6000 Ada
	Memory	20GB GDDR6 memory,160-bit, Bandwidth: Up to 360 GB/s	32GB GDDR6 memory, 256-bit, Bandwidth: Up to 576 GB/s	48GB GDDR6 memory, 384-bit, Bandwidth: Up to 960 GB/s
	ECC	Yes	Yes	Yes
GPGPU Computing	CUDA® Cores	6,144 CUDA® Cores, 26.7 TFLOPS SP Peak	12,800 CUDA® Cores, 65.3 TFLOPS SP Peak	18,176 CUDA® Cores, 91.1 TFLOPS SP Peak
	Tensor Cores	192, 428 AI TFLOPS	400, 1044 TFLOPS	568, 1457 TFLOPS
	RT Cores	48	100	142
	Compute API	CUDA® Toolkit 12.2, Direct Compute, OpenCL™ 3.0		
	Graphics API	Shader Model 6.7, OpenGL® 4.6, DirectX 12, Vulkan® 1.3		
Display	Display Outputs	4x DP 1.4 digital video outputs (DP++), 4x 4096 x 2160 @120Hz, 4x 5120 x 2880 @60Hz, 2x 7680 x 4320 @60Hz		
	Interface	PCIe Gen4 x16		

Product Selection Guide

3.5" Single Board Computers

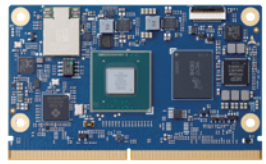


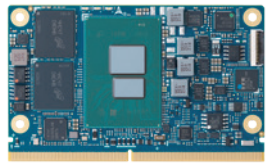


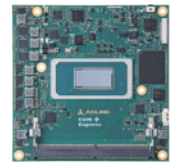
Model	SBC35-MTL	SBC35-ASL
CPU	MTL-U, 15W /MTL-H, 28W	X7433RE, 4 cores, 3.4GHz, 9W
Memory	2x DDR5 SO-DIMMs 5600MHz, up to 96 GB, non-ECC	1x DDR5 SO-DIMMs, up to 4800MHz, up to 16GB
OS Support	Win10/ Win11 24H2 LTSC Ubuntu 22.04LTS (support by project)	Windows® 10/11 (64bit) Ubuntu 22.04 (Support by project)
Display	4 (HDMI, DP, Type-C, LVDS/eDP) eDP x1 (LVDS through RPL driving board)	3 (HDMI, DP, LVDS/eDP(default LVDS))
Controller/ Frequency	2x Intel® I226V,2.5Gps / 1Gbps / 100Mbps / 10Mbps	2x Intel® i210IT, 1Gbps/ 100Mbps / 10Mbps
I/O Interfaces	2x USB 3.2 Gen 2, 3x USB 2.0 (incl. Type-C with DP, 5V/3A) 2x RS-232/422/485, Realtek ALC888S Audio 1x SATA 6Gb/s with 5V power M.2: 2280 M-Key (PCIe x4), 2230 E-Key (PCIe/USB), 3042 B-Key (USB/PCIe) with SIM 8-bit GPIO, TPM 2.0 (optional)	1x USB 3.2 Gen 2, 3x USB 2.0 (rear) 4x COM: RS-232/422/485 (rear & 40-pin headers) 1x SATA 6Gb/s with 5V power Realtek ALC888S Audio (line-in/out, mic-in via 40-pin header) M.2: 2280 M-Key (PCIe x2), 2230 E-Key (Wi-Fi/BT), 3042 B-Key (USB) with SIM 8 DI / 8 DO (40-pin header), TPM 2.0 (optional)
SBC-FM Board Expansion	1x PCIex1 1x PCIe x4 (up to Gen3) 1x USB 3.0/2.01x eSPI	1x PCIex1 1x PCIe x4 (up to Gen3)Support LPC 1x USB 2.0
Dimension	5.75” x 4” (146mm x 102mm)	5.75” x 4” (146mm x 102mm)
Operating Temperature	0 to 60°C	-40°C to 85°C
Storage Temperature	-40°C to 85°C	-40°C to 85°C
Power Supply	12V-24V Connector type: 2x2 connector + DC JACK co-lay	12V-24V Reserve DC JACK connector (option)
ESD	Contact +/-8 KV, Air +/-12 KV	Contact +/-4 KV, Air +/-8 KV
Certification	CE & FCC Class B	CE & FCC Class B

Product Selection Guide

Computer-On-Module™





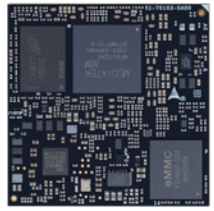


Model Name	LEC-IMX95	LEC-ASL	cExpress-MTL
CPU	NXP i.MX95 series hexa core Cortex A55 1x cortex M33	Intel® Atom® x7000RE/C SoC (8x CPU, 1x GPU)	Intel® Core™ Ultra SoC (14x CPU, 8x GPU, 1x NPU)
Memory/Storage	Up to 8GB LPDDR5, up to 256 GB eMMC	Up to 16GB LPDDR5	up to 96GB SO-DIMM DDR5, NVMe SSD
Cache	Unified 512KB system L3 cache	6MB	24MB
Boot Loader	Uboot + device tree	BIOS	BIOS
Graphics Outputs	LVDS 4L / DSI 4L	LVDS 4L	USB4/HDMI/DP/LVDS/VGA
Camera	1x MIPI CSI	1x MIPI CSI	1x MIPI CSO camera, 4 lanes
LAN	2x RGMII with TSN / 1x 10GbE	2x 2.5GbE with TSN	1x 2.5GbE
USB	2x USB 3.0 3x USB 2.0, 1x OTG	2x USB 3.2 4x USB 2.0	2x USB 3.2 6x USB 2.0
Extension Ports	4x UART 2x SPI 4x I2C 1x SDIO 2x CAN 14x GPIO	4x UART 2x SPI 4x I2C 1x SATA 2x CAN 14x GPIO	2x UART 2x SATA 1x SPI 1x SDIO 1x I2C 8x GPIO
Audio	I2S audio interface	HDA audio interface	HDA audio interface
PCI Express	2x Gen3 x1	4x Gen3 x1	1x Gen4 x8, 2x Gen4 x4
SEMA Support	NA	yes	yes
Power Supply	5.0 V DC±5%	5.0 V DC±5%	12.0 V DC±5%
Operating Temperature	-40°C to +85°C	-40°C to +85°C	-40°C to +85°C
Form Factor & Compatibility	SMARC R2.2 Size L 82 x 50 mm	SMARC R2.2 Size L 82 x 50 mm	PICMG COM.0: R3.1 95 x 95mm
OS Support	Yocto Linux / Android	Windows / Yocto Linux	Win 10 Enterprise, Yocto Linux, Ubuntu

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Product Selection Guide

Open Standard Module™





Model Name	OSM-MTK510	OSM-IMX93
CPU	MediaTek Genio 510 SoC (2x Arm Cortex-A78+ 4x Arm Cortex-A55 cores)	NXP i.MX93 series Dual core Cortex A55 1x cortex M33
Memory/Storage	Up to 8GB LPDDR4; up to 128GB eMMC	Up to 2GB LPDDR4, up to 128 GB eMMC
Cache	-	512KB system L2 cache
Boot Loader	U-boot	Uboot + device tree
Graphics Outputs	HDMI/DP and eDP/DSI 4L	LVDS 4L / DSI 4L
Camera	1x MIPI CSO camera, 4 lanes	1x MIPI CSI
LAN	1x Gbe RGMII	2x RGMII with TSN
USB	2x USB 2.0 1x USB 3.1 Gen 1	2x USB 2.0, 1x OTG
Extension Ports	4x UART 3x SPI / 2x I2C 17x GPIO 2x SDIO 1x PWM	3x UART 2x SPI 2x I2C 1x SDIO 2x CAN 10x GPIO
Audio	1x I2S	I2S audio interface
PCI Express	1x Gen 2 x1	NA
SEMA Support	yes	NA
Power Supply	5.0 V DC±5%	5.0 V DC±5%
Operating Temperature	-40°C to +85°C	-40°C to +85°C
Form Factor & Compatibility	OSM R1.1 Size L 45 x 45 mm	OSM R1.1 Size L 45 x 45 mm
OS Support	Yocto Linux	Yocto Linux

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Product Selection Guide

Industrial Touch Monitors





Model Name	OM Series	IM Series
Mechanical	Open Frame Design	Standalone Design
Display Size	7"-43"	15"-27"
Aspect Ratio	4:3/5:3/5:4/16:9/16:10	4:3/5:4/16:9
Brightness	Up to 1,200 nits	
Backlight Life	Up to 50,000 Hrs	
Touchscreen	10-point, PCAP, Anti-fingerprint coating	
Bonding	Air bonding (Optical bonding optional)	
USB Port	USB type B (for touch)	
Video	HDMI x1, VGA x1	
Audio	w/o Audio	
Operating Temp.	Up to -20°C to 70°C	
Surface Hardness	7H	
IP Rating	Front IP65	
Mounting	Panel, VESA, and Wall	VESA and Wall

** More functions and enhancements are available through Value-Added Service.*

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